

Descriptions

This -30V,-22A P-Channel MOSFET in a DFN 3×3-8L Plastic Package.

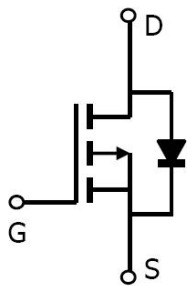
Features

- $V_{DS} (V) = -30V$
- $I_D = -22 A (V_{GS} = -20V)$
- Halogen-Free Product

Applications

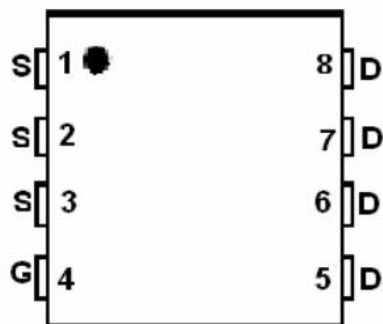
Power Management in Notebook computer, Portable Equipment and Battery powered systems

Equivalent Circuit

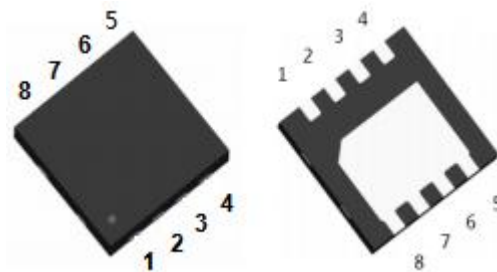


Schematic diagram

Pinning



Pin assignment



DFN3X3-8L

Absolute Maximum Ratings(Ta=25°C)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DSS}	-30	V
Gate-Source Voltage	V_{GSS}	± 20	V
Continuous Drain Current	$I_D (T_a=25^\circ\text{C})$	-22	A
Continuous Drain Current	$I_D (T_a=70^\circ\text{C})$	-18	A
Pulsed Drain Current	I_{DM}	-64	A
Avalanche energy L=0.5mH	E_{AS}	270	mJ
Power Dissipation for Single Operation	$P_D (T_a=25^\circ\text{C})$	22.7	W
Power Dissipation for Single Operation	$P_D (T_a=100^\circ\text{C})$	10	W
Maximum Junction Temperature	T_j	150	°C
Storage Temperature Range	T_{stg}	-55 ~ 150	°C
Thermal Resistance-Junction to Ambient	$R_{\theta JA} (t \leq 10s)$	30	°C/W
Thermal Resistance-Junction to Ambient	$R_{\theta JA}$	60	°C/W
Maximum Junction-to-Case	$R_{\theta JC}$	5.5	°C/W

Electrical Characteristics(Ta=25°C)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$I_D=-250\mu A$ $V_{GS}=0V$	-30			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=-30V$ $V_{GS}=0V$			-1.0	μA
		$V_{DS}=-30V$ $V_{GS}=0V$ $T_J=55^\circ C$			-5.0	
Gate-Body leakage current	I_{GSS}	$V_{DS}=0V$ $V_{GS}=\pm 20V$			± 10 0	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$ $I_D=-250\mu A$	-1.0	-1.7	-3.0	V
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=-10V$ $I_D=-10A$		17.6	20	m Ω
		$V_{GS}=-4.5V$ $I_D=-10A$		26.4	30	
Forward Transconductance	g_{FS}	$V_{DS}=-5V$ $I_D=-10A$		17		S
Diode Forward Voltage	V_{SD}	$I_S=-1A$ $V_{GS}=0V$		-0.72	-1.0	V
Maximum Body-Diode Continuous Current	I_S				-22	A
Total Gate Charge	$Q_{g(10V)}$	$V_{GS}=-10V$ $V_{DS}=-15V$ $I_D=-12A$		21	34	nC
Total Gate Charge	$Q_{g(4.5V)}$			11	18	
Gate-Source Charge	Q_{gs}			6		
Gate-Drain Charge	Q_{gd}			3		
Gate Resistance	R_g	$V_{GS}=0V$ $V_{DS}=0V$ $f=1MHz$		2.0	5.0	Ω
Input Capacitance	C_{iss}	$V_{GS}=0V$ $V_{DS}=-15V$ $f=1MHz$		1650		pF
Output Capacitance	C_{oss}			330		
Reverse Transfer Capacitance	C_{rss}			220		
Turn-on Delay Time	$t_{d(ON)}$	$V_{GS}=-10V$ $V_{DS}=-15V$ $R_L=1.3\Omega$ $R_{GEN}=3\Omega$		10.5		ns
Turn-on Rise Time	t_r			8.5		
Turn-off Delay Time	$t_{d(OFF)}$			30		
Turn-off Fall Time	t_f			11.5		
Body Diode Reverse Recovery Time	t_{rr}	$I_F=-12A$ $di/dt=500A/\mu s$		10		ns
Body Diode Reverse Recovery Charge	Q_{rr}	$I_F=-12A$ $di/dt=500A/\mu s$		15		nC

Electrical Characteristic Curve

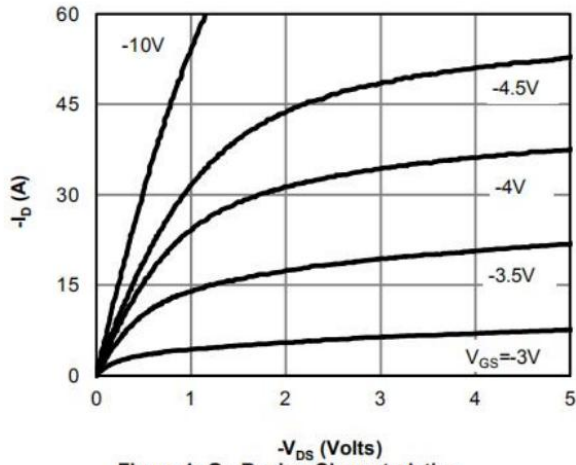


Figure 1: On-Region Characteristics

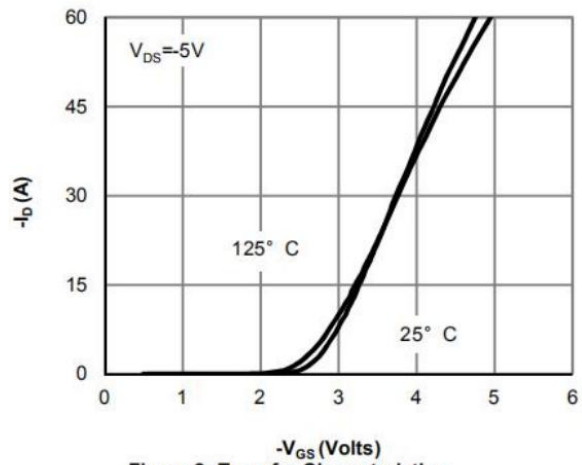


Figure 2: Transfer Characteristics

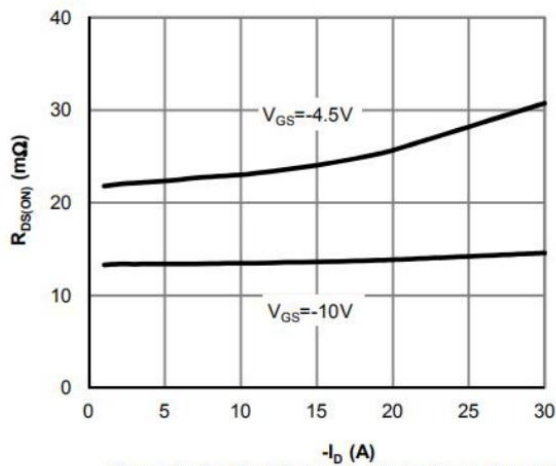


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

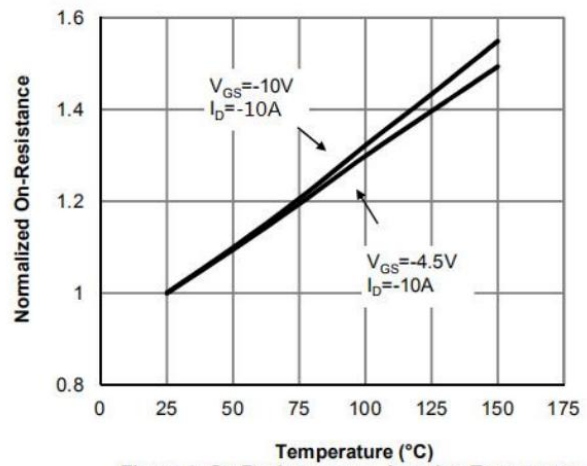


Figure 4: On-Resistance vs. Junction Temperature

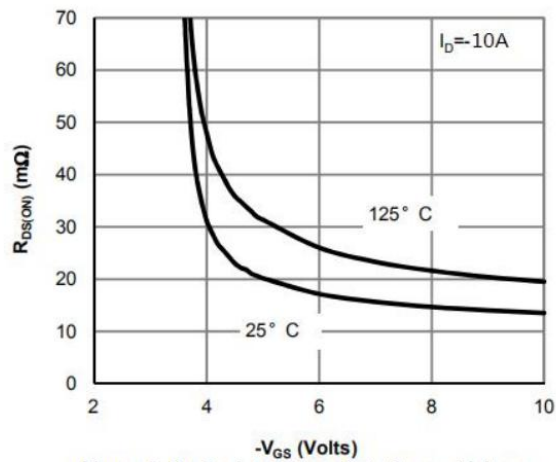


Figure 5: On-Resistance vs. Gate-Source Voltage

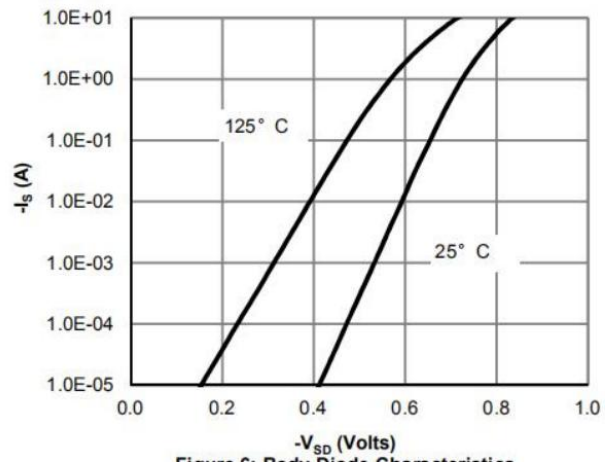


Figure 6: Body-Diode Characteristics

Electrical Characteristic Curve

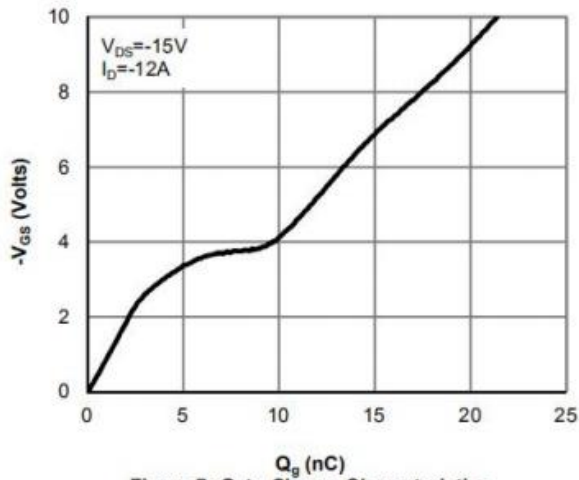


Figure 7: Gate-Charge Characteristics

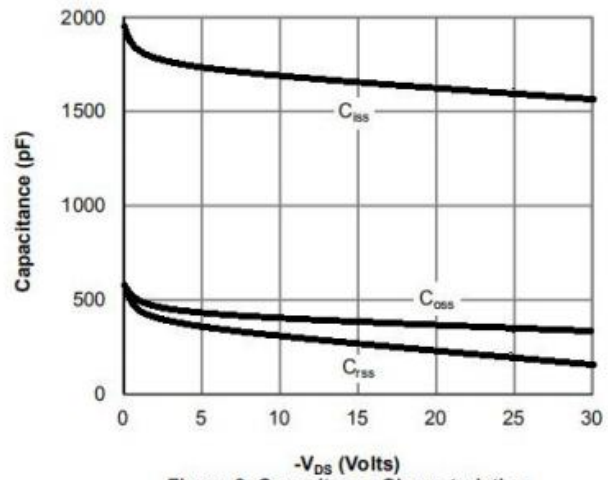


Figure 8: Capacitance Characteristics

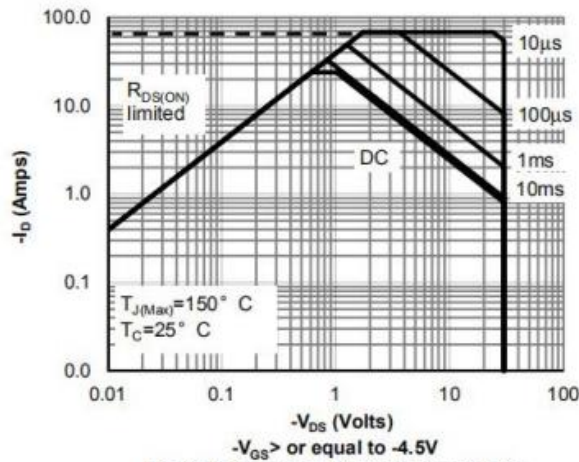


Figure 9: Maximum Forward Biased Safe Operating Area

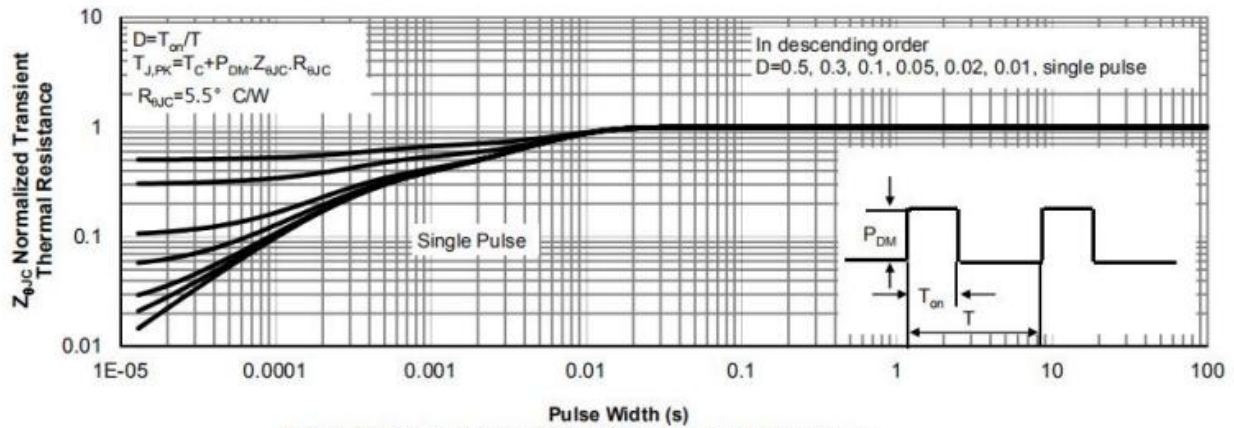
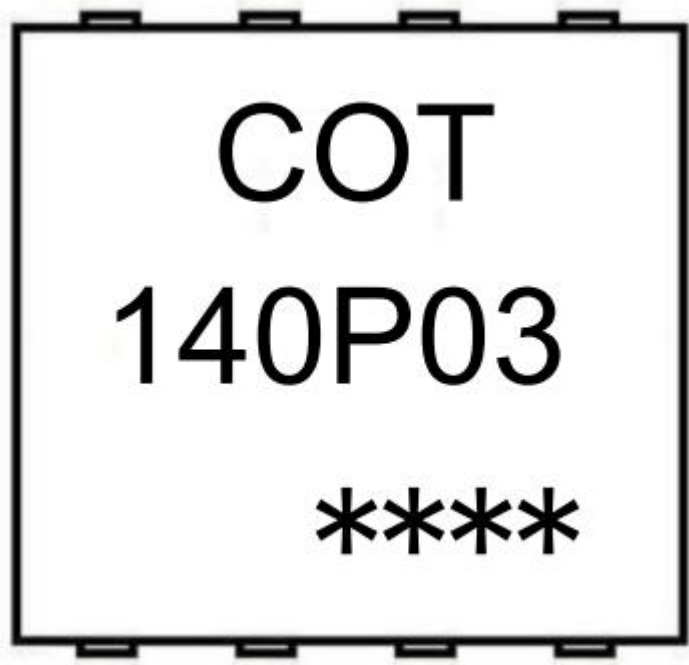


Figure 10: Normalized Maximum Transient Thermal Impedance

Marking Instructions



- Note:
- COT: Company Logo
 - 140P03: Product Type.
 - ****: Lot No. Code, code change with Lot No.

Packaging SPEC

REEL INFORMATION

Package Type	Units					Dimension (unit: mm ³)		
	Units/Reel	Reels/Inner Box	Units/Inner Box	Inner Boxes/Outer Box	Units/Outer Box	Reel	Inner Box	Outer Box
DFN3×3-8L	5,000	2	10,000	6	60,000	13" ×12	360×360×50	380×335×366

Package Outline Dimensions

DFN3X3A-8L

Unit:mm

